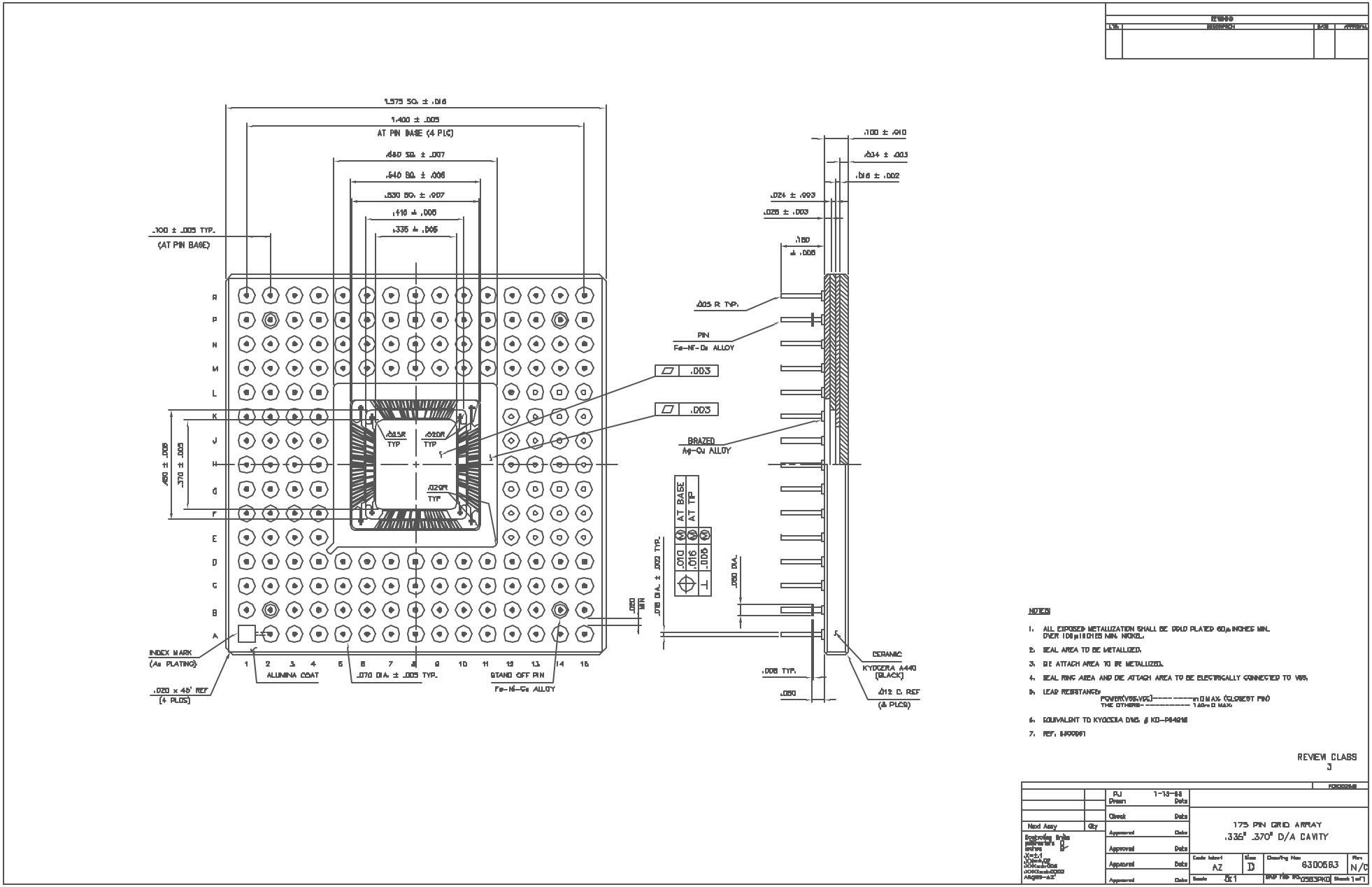
SSM P/N CPG17501



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SSM P/N CPG17501

W/B NO.	PIN NO.
1	VCC
2	C2
3	D4
4	A2
5	C3
6	C5
7	B2
8	VSS
9	C4
10	B3
11	A5
12	A3
13	B6
14	B4
15	VCC
16	A4
17	B5
18	VSS
19	A6
20	C7
21	A8
22	B7
23	VCC
24	A7
25	B8
26	B9

W/B NO.	PIN NO.
27	A9
28	B10
29	C9
30	A11
31	A10
32	A12
33	C10
34	A13
35	B11
36	B12
37	C11
38	VSS
39	C12
40	B13
41	A14
42	VCC
43	D12
44	C13
45	B14
46	D13
47	B15
48	VSS
49	C14
50	E13
51	A15
52	C15

W/B NO.	PIN NO.
53	D14
54	E14
55	VCC
56	E15
57	G13
58	D15
59	G14
60	F14
61	G15
62	F15
63	H15
64	H14
65	VSS
66	J15
67	J14
68	J13
69	K15
70	L15
71	K14
72	N15
73	L14
74	VCC
75	L13
76	M15
77	M14
78	M13

W/B NO.	PIN NO.
79	N14
80	P15
81	VSS
82	VCC
83	N13
84	M12
85	R14
86	R15
87	P13
88	P14
89	N11
90	N12
91	P12
92	R13
93	R9
94	R12
95	R8
96	P11
97	VSS
98	R11
99	P10
100	N9
101	VCC
102	R10
103	P9
104	P8

W/B NO.	PIN NO.
105	P7
106	VSS
107	R6
108	N7
109	R7
110	P6
111	VSS
112	R5
113	N6
114	VCC
115	P5
116	N5
117	R4
118	N4
119	R3
120	P3
121	P4
122	R2
123	VSS
124	R1
125	VCC
126	VSS
127	N3
128	M4
129	P1
130	P2

W/B NO.	PIN NO.
131	L3
132	M3
133	VSS
134	N2
135	N1
136	VCC
137	M2
138	M1
139	L1
140	L2
141	K2
142	J2
143	K1
144	J1
145	J3
146	H3
147	VSS
148	H2
149	H1
150	VCC
151	G1
152	G2
153	VSS
154	G3
155	F2
156	F1

W/B NO.	PIN NO.
157	F3
158	E2
159	E1
160	E3
161	D1
162	D3
163	D2
164	B1
165	C1
166	VSS

	DATE	APPROVAL

PJ 1-13-88 Drawn Date
Check Date
Approved Date
Approved Date
Approved Date
Approved Date

Next Assy | Qty

175 PIN GRID ARRAY
.336" .370" D/A CAVITY

Code Ident AZ | Size D | Dwg No. 6300583 | Rev N/C
Scale 2:1 | SAP File No. 0583PKG | Sheet 1 of 1

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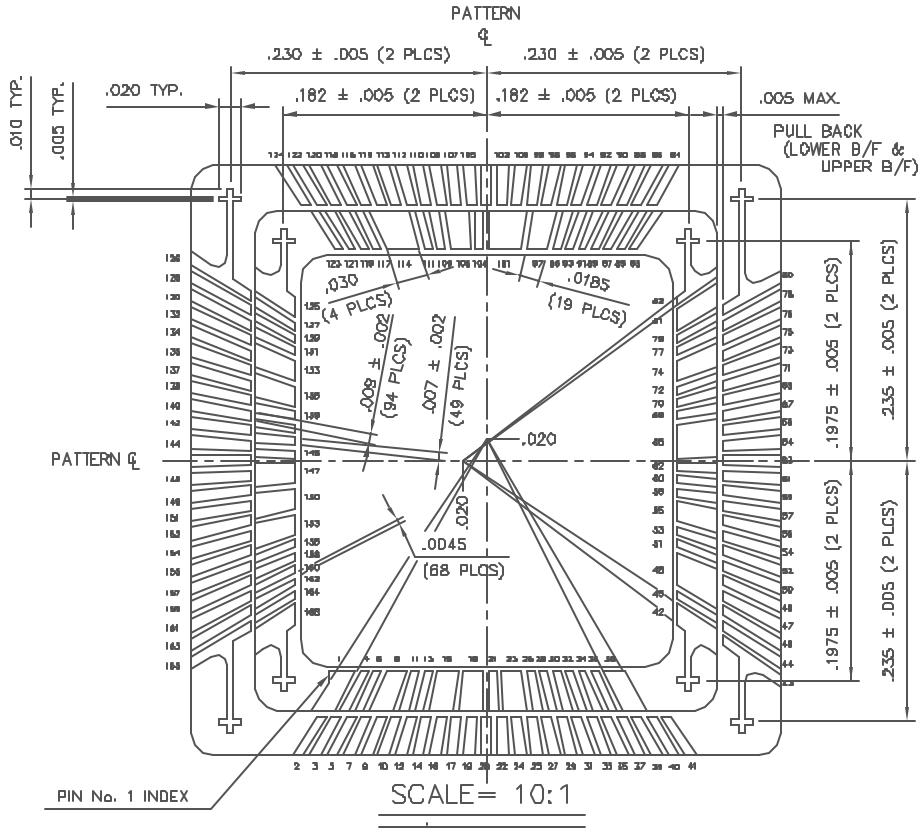
SSM P/N CPG17501



VSS	C6,D6,D8,D10,F4,F12,F13, H4,H12, K3,K4,K12,K13 M6,M8,M10,N10, S/R.D/A
VCC	C8,D5,D7,D9,D11,E4,E12, G4,G12,J4,J12,L4,L12,M5, M7,M9,M11,N8,H13

NOTES:

1. ALL EXPOSED METALLIZATION SHALL BE GOLD PLATED 40μ INCHES MIN. OVER 100μ INCHES MIN. NICKEL.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALIZED.
4. SEAL RING AREA AND DIE ATTACH AREA TO BE ELECTRICALLY CONNECTED TO VSS.
5. LEAD RESISTANCE:
   POWER(VSS,VCC)---------mΩ MAX. (CLOSEST PIN)
   THE OTHERS---------- 140mΩ MAX.
6. EQUIVALENT TO KYOCERA DWG. # KD-P94916
7. REF. 6300051

REVIEW CLASS 3

Next Assy	Qty	PJ 1-13-94 Drawn Date	175 PIN GRID ARRAY .336" .370" D/A CAVITY
		Check Date	
		Approved Date	
		Approved Date	
		Approved Date	
		Approved Date	
		Code Ident AZ	Size D
		Scale 5:1	Dwg/Prg No. 6300583
		EAP File No. 0583PKD	Rev N/C
			Sheet 1 of 1

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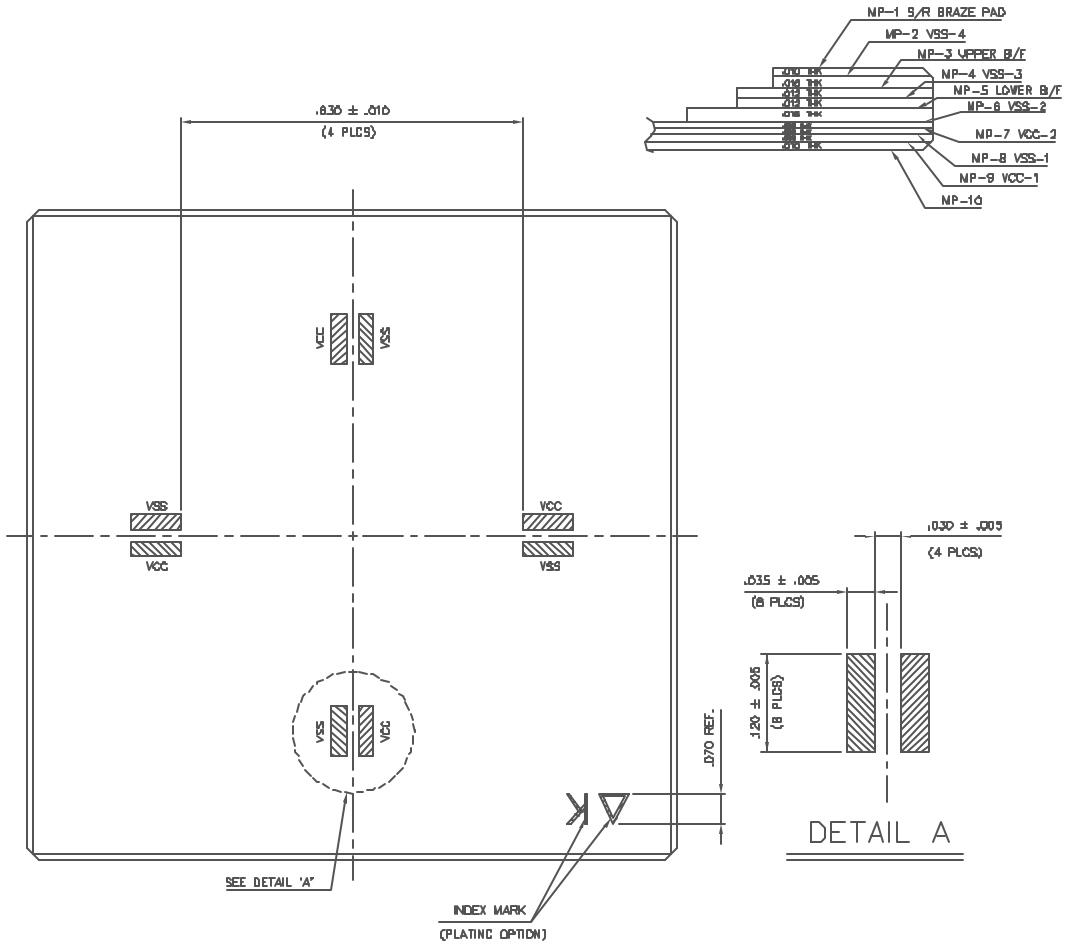
SSM P/N CPG17501



PACKAGE LAY UP

NOTES:

1. ALL EXPOSED METALLIZATION SHALL BE GOLD PLATED 60μ INCHES MIN. OVER 100μ INCHES MIN. NICKEL.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AREA AND DIE ATTACH AREA TO BE ELECTRICALLY DONNECTED TO VSS.
5. LEAD RESISTANCE:
   POWER(VSS,VCC) ---------m Ω MAX. (CLOSEST PIN)
   THE OTHERS---------- 140mΩ MAX.
6. EQUIVALENT TO KYOCERA DWG. # KD-P84916
7. REF. 8300061

REVIEW CLASS
3

Next Assy	Qty	PJ 1-13-94 Drawn Date	175 PIN GRID ARRAY .336" .370" D/A CAVITY
Dimensions in inches unless otherwise specified		Check Date	
		Approved Date	
		Approved Date	
		Approved Date	
		Approved Date	
		Code Ident AZ	Size D
		Scale DI	Drawing No. 8300583
			Rev N/C
			Sheet 1 of 1